



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Shau-Lin Shue et al.

Serial No.: 10/812,734

Filed: March 30, 2004

For: Method For Forming A Self-  
Passivated Copper Interconnect  
Structure

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Attorney Docket No.: 24061.587  
(2000-0101C)

Customer No.: 42717

Group Art Unit: 2824

Examiner: Quach, Tuan N

Conf. No.: 4809

TRANSMITTAL

Mail Stop: Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

1. Amendment in Response to the Office Action dated November 23, 2004;
2. Check in the amount of \$200;
3. This transmittal (in duplicate); and
4. Return postcard.

The Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell  
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Date: 2-21-05

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:

Bonnie Boyle

2-21-05  
Date

